

REMARKS/ARGUMENTS

The foregoing amendment seeks to replace Table 2 with a corrected version showing the correct number of examples; namely, 11 and the correct name for γ -glycidoxypentyl-trimethoxysilane. A copy of the Table 2 as amended on Feb. 6, 2006, is attached showing the strike through of the incorrect spelling of γ -glycidoxypentyl-trimethoxysilane.

The amendment of October 30, 2006, contained the incorrect number of examples and failed to take into account that Table 2 had been corrected previously in the amendment of February 6, 2006 to show the correct number of examples as 11 instead of 15.

Correction of the record is therefore respectfully requested.

Respectfully submitted,

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TABLE 2

	Comparative Example										
	1	2	3	4	5	6	7	8	9	10	11
Phenol biphenylarylate type epoxy resin	7.4	9.4		7.4	7.5	7.6	7.35	7.35	7.4	7.35	7.35
Biphenyl type epoxy resin											
Cresol novolac type epoxy resin			6.9								
Phenol biphenylarylate resin	5.5			5.5	5.52	5.65	5.5	5.5	5.5	5.5	5.5
Phenolarylate resin			6.0								
Phenol novolac resin		3.5									
Spherical fused silica	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
7-allyl-4-vinyl-2,2,4,4-tetramethyl-1,3-dioxane	0.4	0.4	0.4		0.4		0.4	0.4	0.4	0.4	0.4
7-allyl-4-vinyl-2,2,4,4-tetramethyl-1,3-dioxane											
Triphenylphosphine	0.2	0.15	0.15	0.2	0.06	0.2	0.2	0.2	0.2		
DBU									0.2	0.25	
Curing accelerator of formula (7)											
Curing accelerator of formula (8)										0.25	
2,2-Dihydroxydiphenylmethane		0.05	0.05			0.05					
1,2-Dihydroxydiphenylmethane											
Catechol											
Pyrogallol							0.05				
1,6-Dihydroxydiphenylmethane								0.05			
Resorcinol	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carnauba wax	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Carbon black	80	76	71	62	114	76	76	81	66	89	77
Spiral flow (cm)											
Curing torque ratio (%)	65	67	70	62	7	56	65	54	57	56	59
Solder resistance-cracking	4	2	chip	3	chip	0	5	4	4	2	3
Chip delamination											
Internal crack											
Fire retardancy	V-0	V-1	HB				V-0	V-0	V-0	V-0	V-0